SECTION HEAT DISSIPATORS FOR PLASTIC CASE, CASE-MOUNTED SEMICONDUCTORS

Horizontally mounted, light-weight, low-cost heat dissipators

- Accommodates all flat plastic case power semiconductors.
- Efficient design requires just .71 sq. in. of board area (PA Series) and .31" to .5" height above board.

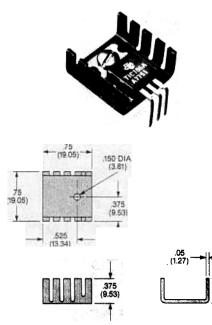
PC1-1CB

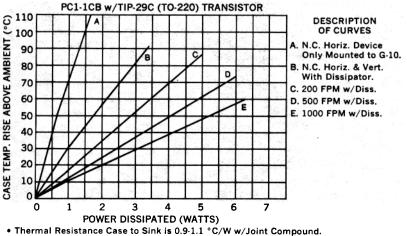
- Larger PB Series offers greater heat dissipation, additional hole patterns, and dual semiconductor mounting capability.
- Only one mounting screw required to secure dissipators to semiconductor and

circuit board.

Most effective heat dissipator in performance/unit cost.

DESCRIPTION





Derate 2.4 °C/watt for unplated part in natural convection only.

PA1-1U w/TIP-29C (TO-220) TRANSISTOR

Ordering Information

.375 (9.53)

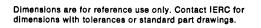
	IERC PART NO.		Max.	
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Semiconductor Accommodated	Weight (Grams)
PC1-1U	PC1-1CB	PC1-1B	T0-126, T0-127, T0-220	1.9

PA1 Series .150 (3.81 DIA, HOL 1.00 Q2 SYM 195.40

Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



(18.03)



ပ္ပ် 110 ၂၀၇ **OF CURVES RISE ABOVE AMBIENT** A. N.C. Horiz, Device 90 Only Mounted to G-10. D 80 B. N.C. Horiz. & Vert. With Dissipator. 70 C. 200 FPM w/Diss. 60 D. 500 FPM w/Diss. E. 1000 FPM w/Diss. 50 40 30 CASE TEMP. 20 10 0 0 2 3 4 5 6 7 8 9 10 11 12 13 14 15 POWER DISSIPATED (WATTS)

• Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.

Uprate 2.4 °C/watt for black part in natural convection only.
Derate 0.6 °C/watt for Insulube® part in natural convection only.

Ordering Information

IERC PART NO.				0	Max.
Unplated	Com'l. Black Anodize	Mil. Black Anodize	Insulube® 448	Semiconductor Accommodated	Weight (Grams)
PA1U PA1-1U	PA1CB PA1-1CB	PA1B PA1-1B	PA1 PA1-1	Undrilled T0-126, T0-127, T0-220	2.0 2.0

Note: See page iv for other finishes.